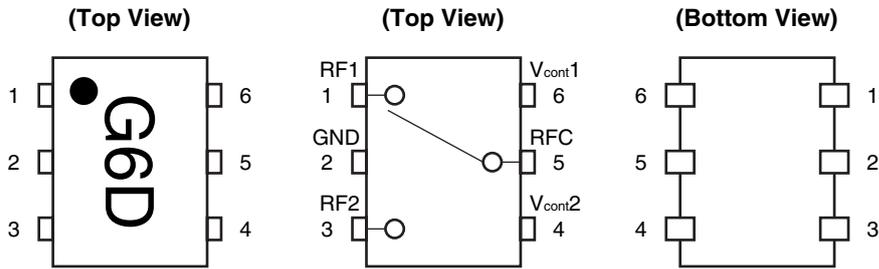


PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	V _{cont2}
5	RFC
6	V _{cont1}

SW TRUTH TABLE

ON Path	V _{cont1}	V _{cont2}
RFC-RF1	High	Low
RFC-RF2	Low	High

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	V _{cont}	+6.0 ^{Note}	V
Input Power (V _{cont (H)} = 3.0 V)	P _{in}	+34.0	dBm
Input Power (V _{cont (H)} = 5.0 V)	P _{in}	+35.0	dBm
Power Dissipation (average)	P _D	0.15	W
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Note |V_{cont1} - V_{cont2}| ≤ 6.0 V

RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f	0.5	-	6.0	GHz
Switch Control Voltage (H)	V _{cont (H)}	2.7	3.0	5.3	V
Switch Control Voltage (L)	V _{cont (L)}	-0.2	0	0.2	V
Control Voltage Difference	ΔV _{cont (H)} , ΔV _{cont (L)} ^{Note}	-0.1	0	0.1	V

Note ΔV_{cont (H)} = V_{cont1 (H)} - V_{cont2 (H)}

ΔV_{cont (L)} = V_{cont1 (L)} - V_{cont2 (L)}

ELECTRICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{\text{cont}}(\text{H}) = 3.0\text{ V}$, $V_{\text{cont}}(\text{L}) = 0\text{ V}$, $Z_0 = 50\ \Omega$, DC blocking capacitors = 8 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L_{ins1}	$f = 0.5\text{ to }2.0\text{ GHz}$ ^{Note 1}	–	0.40	0.65	dB
Insertion Loss 2	L_{ins2}	$f = 2.0\text{ to }2.5\text{ GHz}$	–	0.45	0.70	dB
Insertion Loss 3	L_{ins3}	$f = 2.5\text{ to }3.8\text{ GHz}$	–	0.55	0.80	dB
Insertion Loss 4	L_{ins4}	$f = 3.8\text{ to }6.0\text{ GHz}$	–	0.65	0.90	dB
Isolation 1	ISL1	$f = 0.5\text{ to }2.0\text{ GHz}$ ^{Note 1}	25	28	–	dB
Isolation 2	ISL2	$f = 2.0\text{ to }2.5\text{ GHz}$	25	28	–	dB
Isolation 3	ISL3	$f = 2.5\text{ to }3.8\text{ GHz}$	25	28	–	dB
Isolation 4	ISL4	$f = 3.8\text{ to }6.0\text{ GHz}$	22	26	–	dB
Return Loss 1	RL1	$f = 0.5\text{ to }2.0\text{ GHz}$ ^{Note 1}	15	20	–	dB
Return Loss 2	RL2	$f = 2.0\text{ to }2.5\text{ GHz}$	15	20	–	dB
Return Loss 3	RL3	$f = 2.5\text{ to }6.0\text{ GHz}$	10	15	–	dB
0.1 dB Loss Compression Input Power ^{Note 2}	$P_{\text{in}}(0.1\text{ dB})$	$f = 0.5\text{ to }2.0\text{ GHz}$ ^{Note 1}	–	+32.0	–	dBm
		$f = 2.0\text{ to }6.0\text{ GHz}$	–	+31.0	–	dBm
		$f = 0.5\text{ to }6.0\text{ GHz}$ ^{Note 1} , $V_{\text{cont}}(\text{H}) = 5.0\text{ V}$	–	+35.0	–	dBm
1 dB Loss Compression Input Power ^{Note 3}	$P_{\text{in}}(1\text{ dB})$	$f = 0.5\text{ to }2.0\text{ GHz}$ ^{Note 1}	–	+34.0	–	dBm
		$f = 2.0\text{ to }6.0\text{ GHz}$	–	+34.0	–	dBm
Input 3rd Order Intercept Point	IIP ₃	$f = 2.5\text{ GHz}$, $P_{\text{in}} = +20\text{ dBm}$	–	+60	–	dBm
2nd Harmonics	2f ₀	$f = 2.5\text{ GHz}$, $P_{\text{in}} = +20\text{ dBm}$	–	80	–	dBc
3rd Harmonics	3f ₀	$f = 2.5\text{ GHz}$, $P_{\text{in}} = +20\text{ dBm}$	–	80	–	dBc
Switch Control Current	I_{cont}	No RF input	–	0.1	10	μA
Switch Control Speed	t _{sw}	50% CTL to 90/10% RF	–	50	250	ns

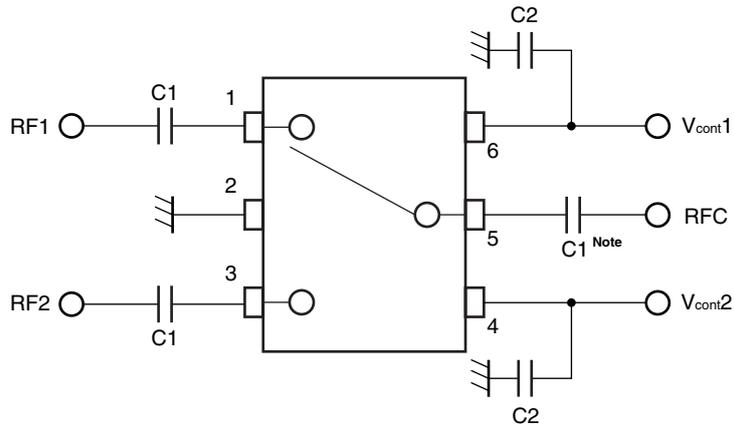
Notes 1. DC blocking capacitors = 56 pF at $f = 0.5\text{ to }2.0\text{ GHz}$

- 2.** $P_{\text{in}}(0.1\text{ dB})$ is the measured input power level when the insertion loss increases 0.1 dB more than that of the linear range.
- 3.** $P_{\text{in}}(1\text{ dB})$ is the measured input power level when the insertion loss increases 1 dB more than that of the linear range.

Caution It is necessary to use DC blocking capacitors with this device.

The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system.

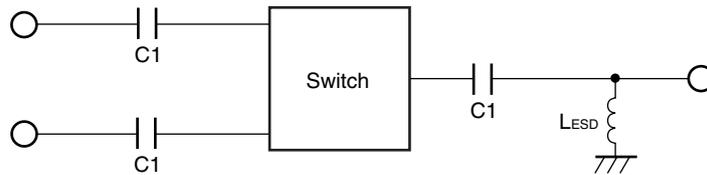
EVALUATION CIRCUIT



Note C1 : 0.5 to 2.0 GHz 56 pF
 : 2.0 to 6.0 GHz 8 pF
 C2 : 1 000 pF

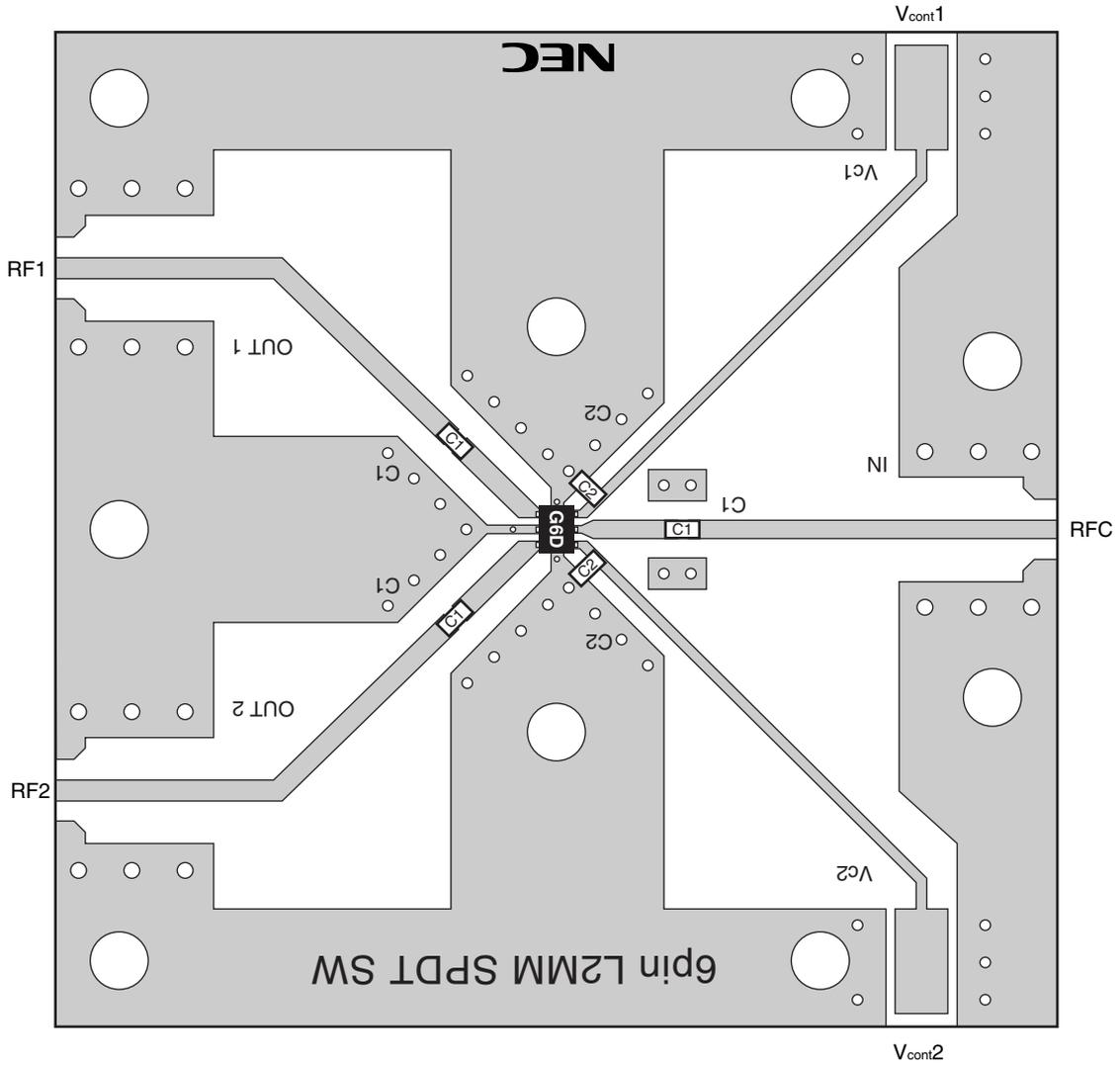
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

APPLICATION INFORMATION



- L_{ESD} provides a means to increase the ESD protection on a specific RF port, typically the port attached to the antenna.
- The value may be tailored to provide specific electrical responses.
- The RF ground connections should be kept as short as possible and connected to directly to a good RF ground for best performance.

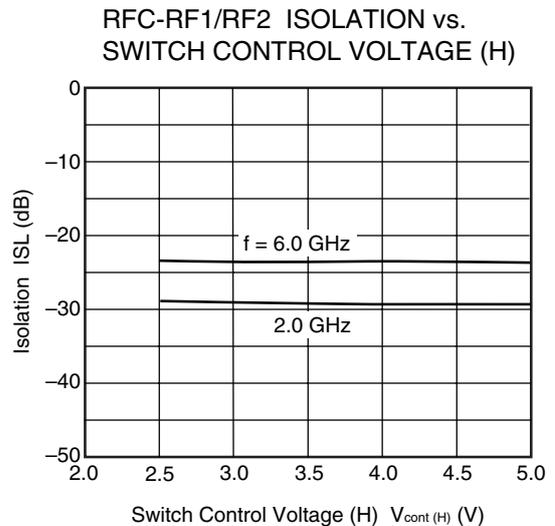
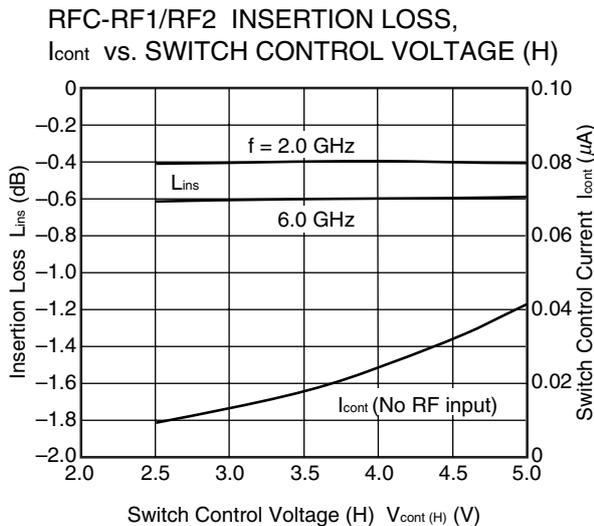
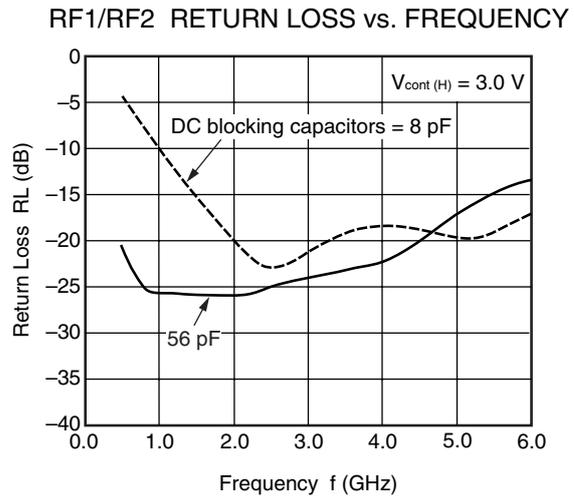
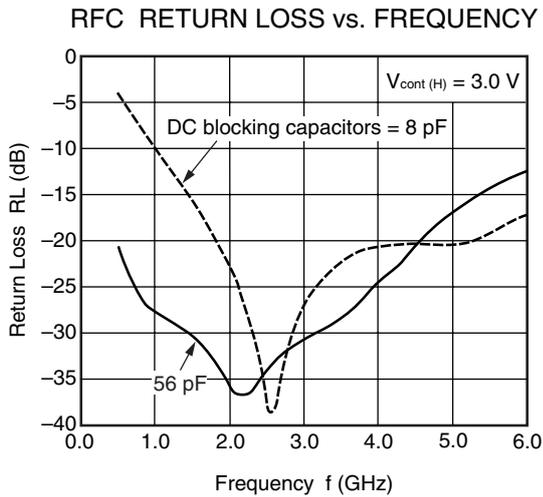
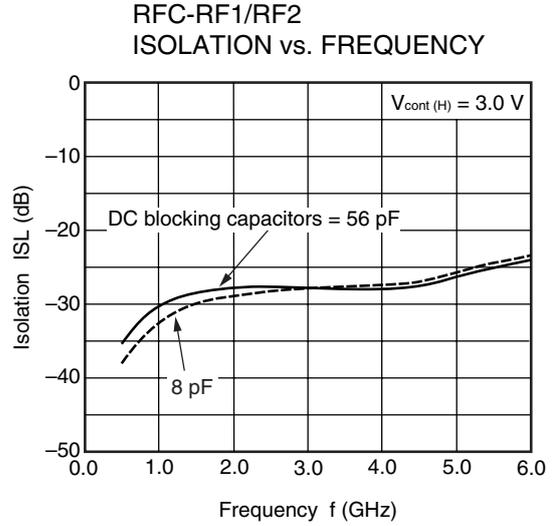
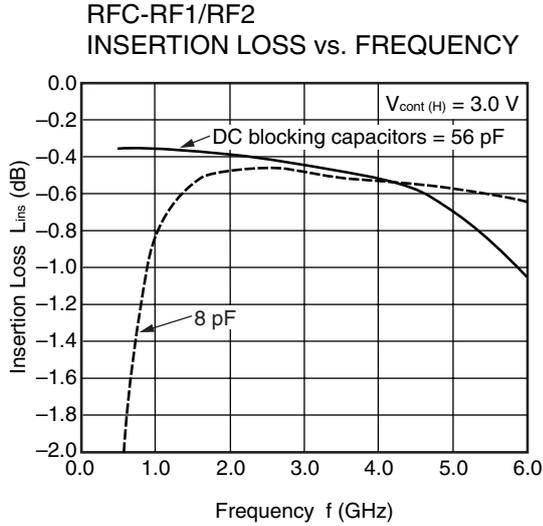
ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



USING THE NEC EVALUATION BOARD

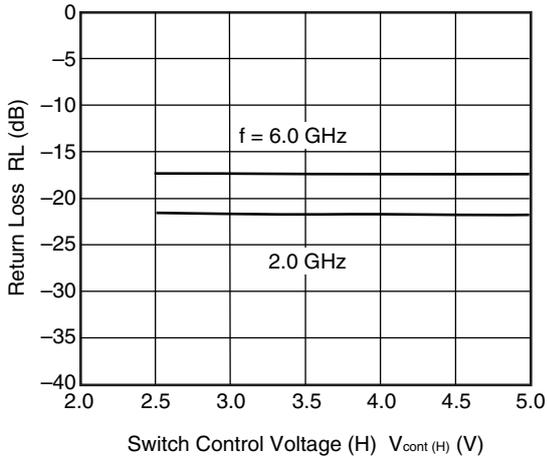
Symbol	Test Conditions	Values
C1	f = 0.5 to 2.0 GHz	56 pF
	f = 2.0 to 6.0 GHz	8 pF
C2		1 000 pF

TYPICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$, $V_{\text{cont (H)}} = 3.0\text{ V}$, $V_{\text{cont (L)}} = 0\text{ V}$, $Z_0 = 50\ \Omega$, DC blocking capacitors = 8 pF, unless otherwise specified)

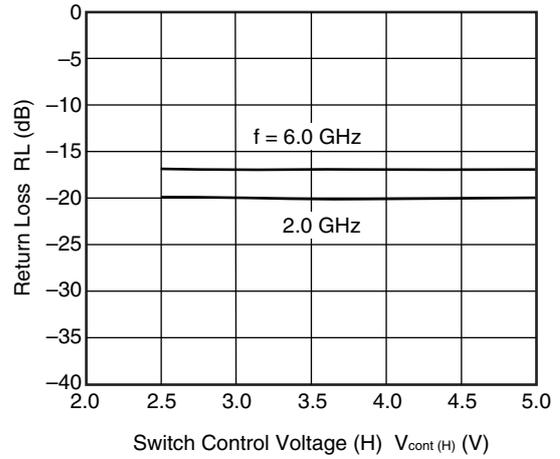


Remark The graphs indicate nominal characteristics.

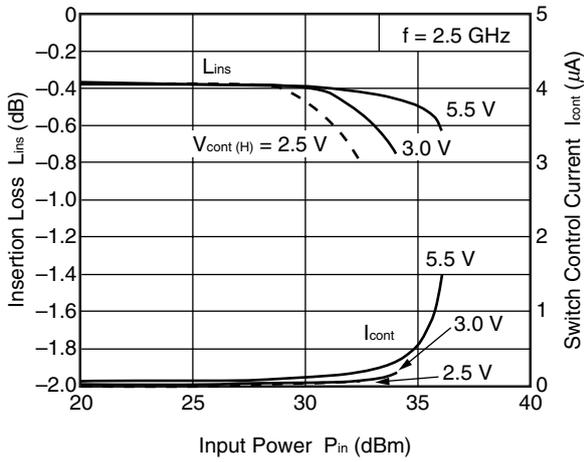
RFC RETURN LOSS vs. SWITCH CONTROL VOLTAGE (H)



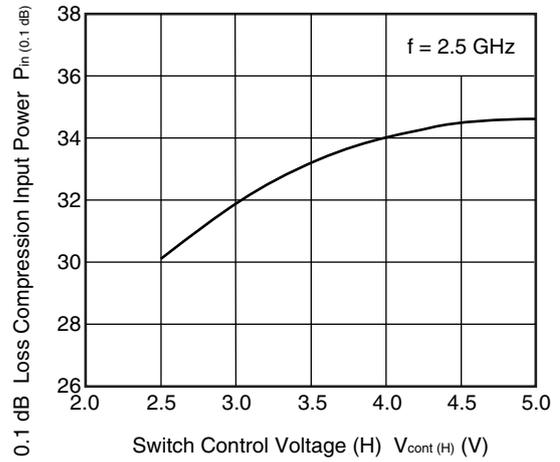
RF1/RF2 RETURN LOSS vs. SWITCH CONTROL VOLTAGE (H)



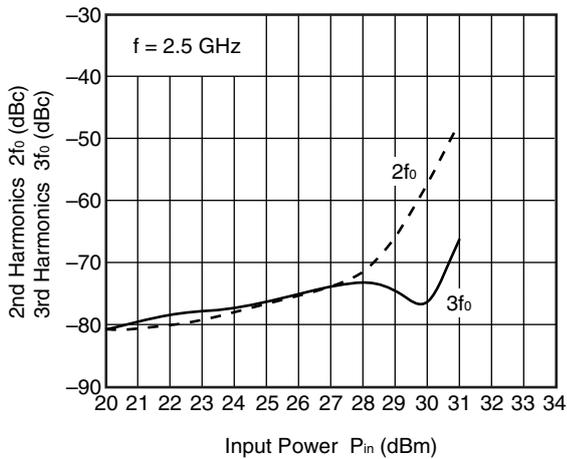
RFC-RF1/RF2 INSERTION LOSS, Icont vs. INPUT POWER



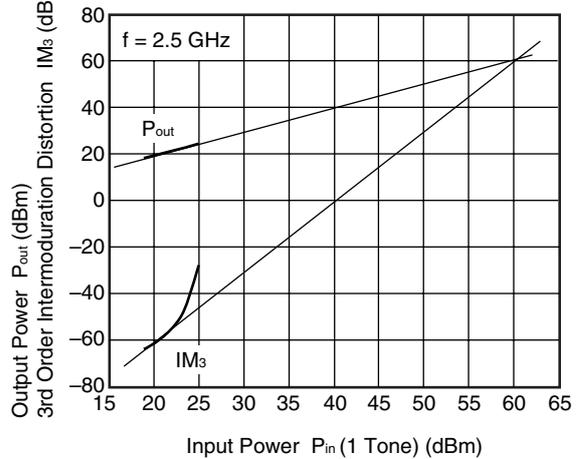
RFC-RF1/RF2 Pin (0.1 dB) vs. SWITCH CONTROL VOLTAGE (H)



RFC-RF1/RF2 2fo, 3fo vs. INPUT POWER



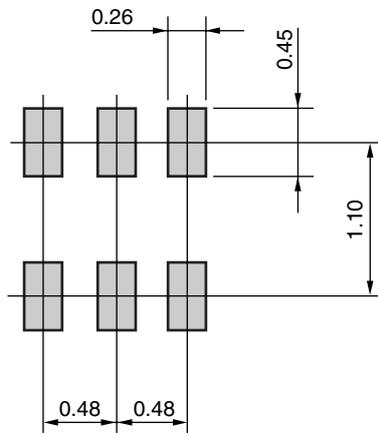
RFC-RF1/RF2 OUTPUT POWER, IM3 vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

MOUNTING PAD LAYOUT DIMENSIONS

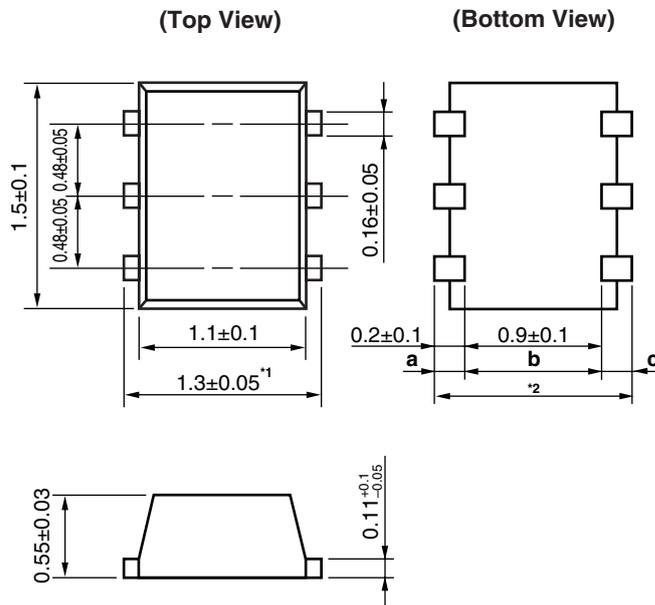
6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)



Remark The mounting pad layout in this document is for reference only.

PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)



Remark Dimension ^{*1} is bigger than dimension ^{*2} (dimension ^{*2} = a + b + c).

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E0904E

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To our customers,

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April 1st, 2010
Renesas Electronics Corporation

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